TSW14J56EVM Test Report

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Figure 1. Board Photo Top
Figure 2. Board Photo Bottom
3) **Efficiency**

The efficiency of the converters is shown in the figures below. The input voltage is set to 5V.

![Efficiency Graph](image-url)

**Figure 3.** VIN = 5V Efficiency
Figure 4. VIN = 5V Efficiency
4) Load Regulation

The images below show the output load regulation. The input voltage is 5V.

Figure 5. VIN = 5V Load Regulation
Figure 6. VIN = 5V Load Regulation
5) Startup No Load

The images below shows the startup waveforms. The output is not loaded. The input voltage is set to 5V.

Figure 7. VIN = 5V Startup with No Load

Figure 8. VIN = 5V Startup with No Load
6) **Output Voltage Ripple**

The images below show the output voltage ripple when load is fully applied. The input voltage is 5V.

![Figure 9. VIN = 5V, VOUT = 0.85V, IOUT = 6A Output Ripple Voltage](image)

![Figure 10. VIN = 5V, VOUT = 1.0V, IOUT = 6A Output Ripple Voltage](image)
Figure 11. VIN = 5V, VOUT = 3.0V, IOUT = 6A Output Ripple Voltage

Figure 12. VIN = 5V, VOUT = 1.5V, IOUT = 6A Output Ripple Voltage
Figure 13. VIN = 5V, VOUT = 1.5V DDR3, IOUT = 6A Output Ripple Voltage

Figure 14. VIN = 5V, VOUT = 3.0V, IOUT = 6A Output Ripple Voltage
7) Load Transients

The transient response of the converters is shown below. The input voltage is 5V. The output current is pulsed from 50% load to full load.

Figure 15. VIN = 5V, VOUT = 0.85V, 3A to 6A Load Transient

Figure 16. VIN = 5V, VOUT = 1.0V, 3A to 6A Load Transient
Figure 17. VIN = 5V, VOUT = 3.0V, 3A to 6A Load Transient

Figure 18. VIN = 5V, VOUT = 1.5V, 3A to 6A Load Transient
Figure 19. VIN = 5V, VOUT = 1.5V, 3A to 6A Load Transient

Figure 20. VIN = 5V, VOUT = 3.0V, 3A to 6A Load Transient
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